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PATENT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of Infantolino et al	)	Examiner:
	)	
Serial No. To be assigned	)	Art Unit:
	)	
Filed: Herewith	)	
	)	
For: SEMICONDUCTOR CHIP MODULE AND	)	
METHOD OF MANUFACTURE OF SAME	)	

Docket No. END920020084US1 (IEN-10-5695)

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

This Information Disclosure Statement is being filed to fulfill the duty of candor and good faith toward the Patent and Trademark Office, as required pursuant to 37 C.F.R. § 1.56.

Listed on the attached PTO form 1449 is information known to persons substantively involved in the preparation of the application identified above, and that a reasonable Examiner would consider important when deciding whether to allow the application. This document is not to be construed as a representation that a search to locate the most relevant information has been made, nor a representation that more pertinent information does not exist.

Copies of the information listed on the attached PTO Form 1449 are provided herewith.

END920020084US1 (IEN-10-5695)

The identification of any information herein is not intended to be, and should not be understood as being, an admission that such information, in fact, constitutes "prior art" within the meaning of applicable law. The "prior art" status of any information is a matter to be resolved during prosecution.

This Information Disclosure Statement is being filed with the application. Accordingly, it is not believed that any fee is required relating to the filing of this Information Disclosure Statement. If this is not the case, the Patent Office is hereby authorized to charge any related fee to Deposit Account No. 03-0172.

Respectfully submitted,

Date: \_\_\_\_\_

9/19/02

By: \_\_\_\_\_

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Enclosures

Subst. Form PTO-1449  APPLICANT'S INFORMATION DISCLOSURE STATEMENT	Atty. Docket No.: END920020084US1 (IEN-10-5695)	Serial No.: To be assigned
	Applicant: Infantolino et al	
	Filing Date: Herewith	Group:

## U.S. PATENT DOCUMENTS

Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
	AA	5,492,586	02/20/96	Gorczyca	156	245	06/24/94
	AB	6,221,694 B1	04/24/01	Bhatt et al	438	122	06/29/99
	AC	6,229,216 B1	05/08/01	Ma et al	257	777	01/11/99
	AD	6,271,469 B1	08/07/01	Ma et al	174	52.4	11/12/99
	AE	6,312,972 B1	11/06/01	Blackshear	438	106	08/09/99
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

## FOREIGN PATENT DOCUMENTS

		Document No.	Date	Country	Class	Subcl.	Translation?
	AL	JP11220061A	08/10/99	Japan			Abstract attached
	AM						
	AN						

## OTHER DOCUMENTS

	AO	IBM Technical Disclosure Bulletin entitled "Flatpack Package Using Core Metal Layer of Composite Substrate as Ground Plane", March, 1991
	AP	
	AQ	
	AR	
	AS	
	AT	

Examiner:

Date Considered:

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if in conformance and not considered.  
Include copy of this form with next communication to applicant